

CMS Power-lines Protection Series (CMS-P)

Descriptions

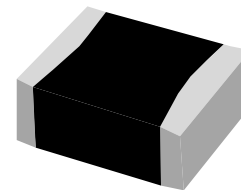
The Ceramic Micro-Surge Protection Device (CMS) is manufactured from semiconducting ceramics which offer rugged protection and excellent transient energy absorption in a small SMD package. These devices are designed to suppress a variety of transient events, including those specified in IEC61000-4-2, IEC61000-4-5 and other standards used for Electromagnetic Compliance (EMC).

These devices are available in ceramic leadless chip form, eliminating lead inductance and assuring fast speed of response to transient surges. In addition, The CMS transient suppressors have temperature independent suppression characteristics, affording protection from -55°C to 125°C, which is much better than suppressors based on silicon semiconductor technology.

The CMS-P Series is specially designed for power-lines protection applications. It features a very high current protection capability with a very small size, also a very fast response thus a ultra low clamping voltage. These characteristics make CMS-P Series devices the best replacement of TVS and improvement of metal oxide (MOV) in high working voltage applications.

Features

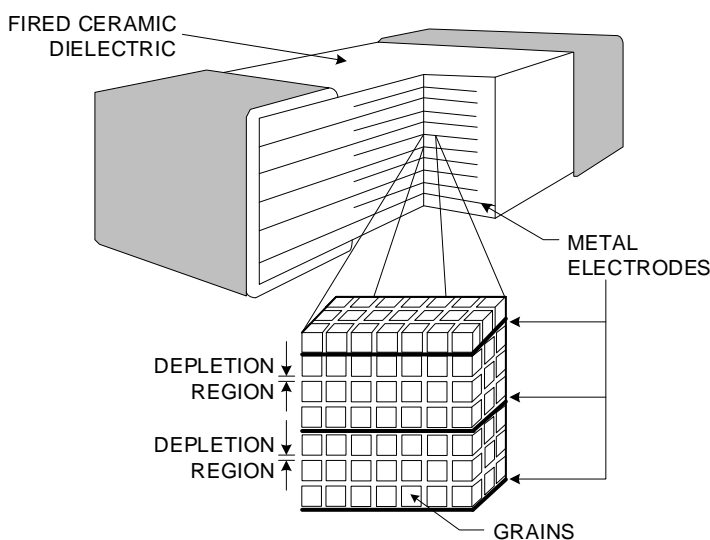
- Multi-Layers Construction Provides Higher Power Dissipation
- Surge Current Capability: 100A (@8/20μs)
- Better than UL94V-0 Flammability Rating
- No Temperature Derating up to 125°C Ambient
- Reliable ESD Protection up to 30kV acc. to IEC61000-4-2
- Inherent Bi-directional Clamping
- SMD type Body size 1206
- “Zero” Lead Inductance
- Very low Clamping Voltage
- RoHS compliant



Top View (1206)

Order Information

Device	Quantity	Reel Size
CMS1206	2000 pcs	7 Inch (178.0mm)



Multilayer Internal Construction

Applications

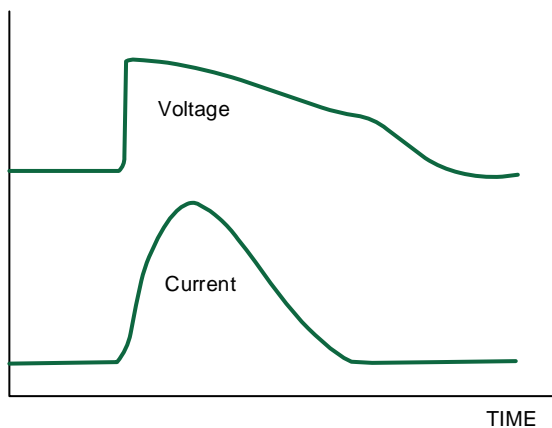
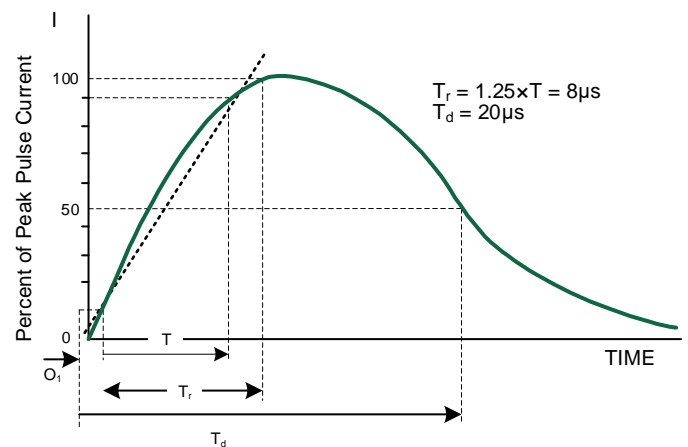
- LED
- Surge protection for IEC/EN 61547
- Surge protection for IEC61000-4-5
- EFT protection for IEC 61000-4-4 (Level 4)
- ESD protection for IEC 61000-4-2 (Level 4)

Agency Information

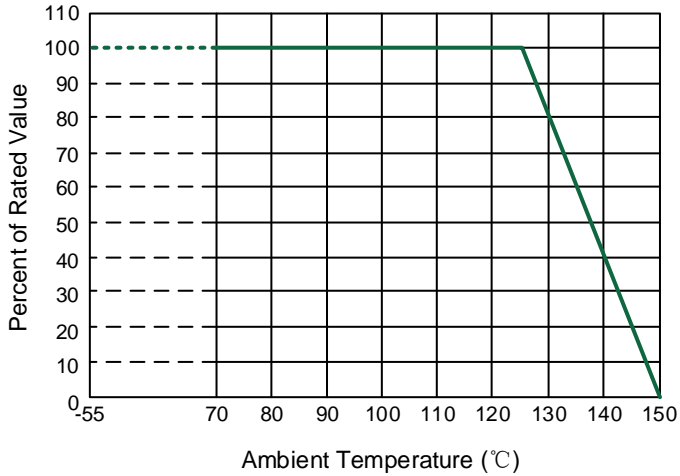
- UL/cUL: E498596
- CQC: CQC21001318502
- TUV: B002653 0001 Rev.01

Device Ratings and Specifications

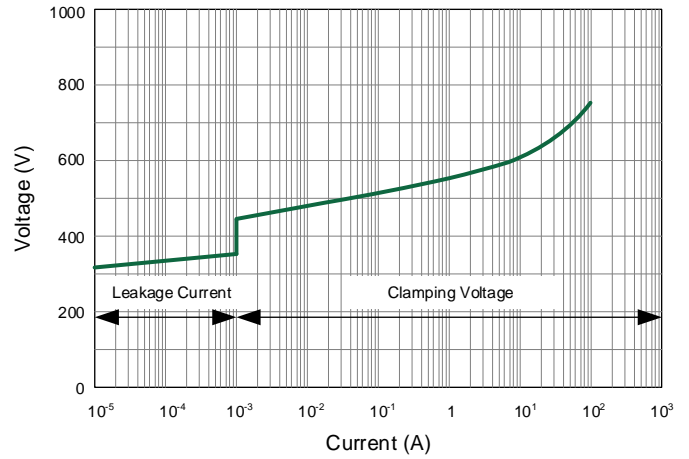
Parameter	Symbol	Condition	Value	Unit
Maximum Continuous a.c. Voltage	$V_{M(AC)}$	50~60Hz	250	V
Maximum Continuous d.c. Voltage	$V_{M(DC)}$		320	V
Nominal Varistor Voltage	V_N	@1mA	351~429	V
Maximum Leakage Current	I_L	@ V_M	30	μA
Maximum Clamping Voltage	V_C	@ I_C	590	V
Class Current	I_C	$t_p = 8/20\mu s$	5	A
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$	100	A
Rated Energy	E_M	10/1000 μs	1.0	J
Operating Temperature Range			-55 to +125	$^{\circ}C$
Storage Temperature			-55 to +150	$^{\circ}C$

Surge Response - 8/20 μs waveform

Pulse Waveform - 8/20 μs waveform


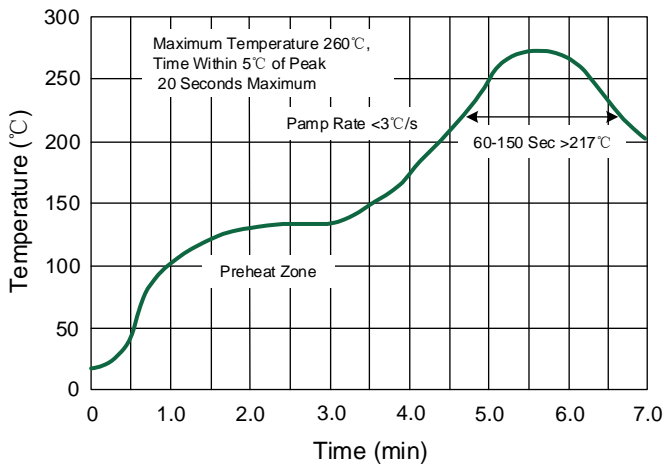
Current, Energy and Power Derating Curve



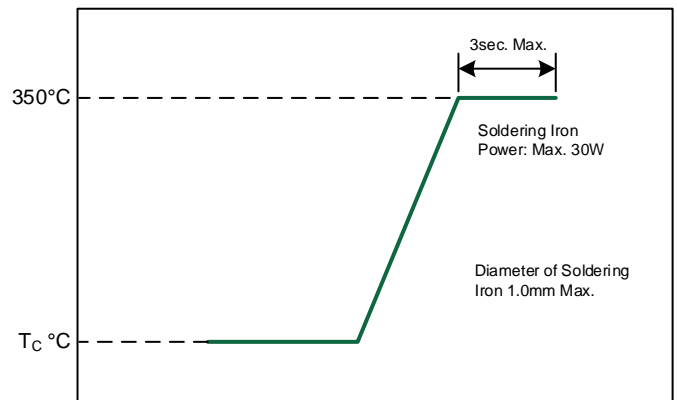
V/I characteristics



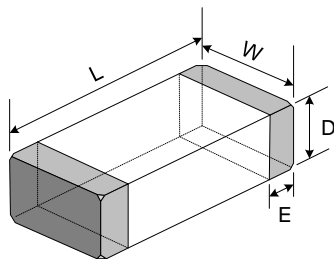
Lead-free Re-flow Solder Profile



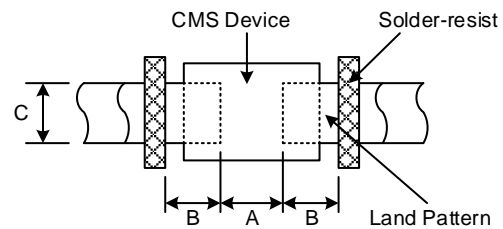
Iron Soldering Profile



Product Dimensions



Product Dimensions



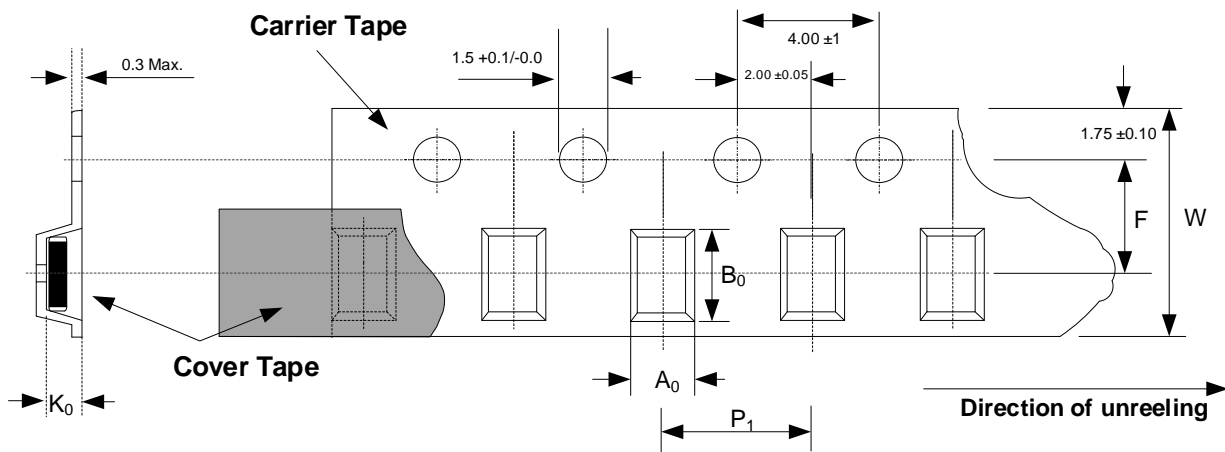
Recommended PCB Pattern

Size	L	W	D	E	A	B	C
1206	3.2 +0.6/-0.2	1.6 +0.4/-0.2	1.3~2.0	0.20~0.75	1.8~2.5	1.0~1.5	1.6~2.2

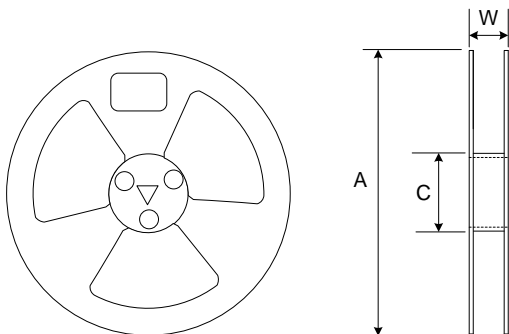
Storage

- Storage temperature range (packaging conditions): -10℃~+40℃ RH 70% (Max.).
- The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40℃ or less and 70% RH or less.
- The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H₂S).
- Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.
- Solderability shall be guaranteed for 12 months from the date of delivery on condition that they are stored at the environment specified in Clause 2. For those parts, which passed more than 12 months shall be checked solder-ability before use.

Tape and Reel Specifications



Type	A ₀	B ₀	K ₀	P ₁	W	F
CMS1206	2.10 ±0.20	3.90 ±0.20	2.20 Max.	4.00 ±0.10	8.00 ±0.20	3.50 ±0.05

Reel Dimension


Spec.	Dimensions(mm)		
	A	W	C
7**8mm	178	8.4+1.5/-0.0	58

Environmental Reliability Test

Item	Requirement	Test Condition
High Temperature Storage	<ul style="list-style-type: none"> Breakdown voltage change: within $\pm 10\%$ No mechanical damage 	<ul style="list-style-type: none"> Temperature: $150 \pm 2^{\circ}\text{C}$ Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Low Temperature Storage	<ul style="list-style-type: none"> Breakdown voltage change: within $\pm 10\%$ No mechanical damage 	<ul style="list-style-type: none"> Temperature: $-55 \pm 2^{\circ}\text{C}$ Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Thermal Shock	<ul style="list-style-type: none"> Breakdown voltage change: within $\pm 10\%$ No mechanical damage 	<ul style="list-style-type: none"> Temperature, Time: $-55 (\pm 2)^{\circ}\text{C}/30\text{min} \sim 125 (\pm 2)^{\circ}\text{C}/30\text{min}$ Transforming interval: 2~3min. Tested cycle: 100 cycles. Test after placing in ambient temperature for 1~2hours
High Temperature Load	<ul style="list-style-type: none"> Breakdown voltage change: within $\pm 10\%$ No mechanical damage 	<ul style="list-style-type: none"> Temperature: $125 \pm 2^{\circ}\text{C}$ Rated working voltage applied Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Damp Heat Load / Humidity Load	<ul style="list-style-type: none"> Breakdown voltage change: within $\pm 10\%$ No mechanical damage 	<ul style="list-style-type: none"> Temperature: $85 \pm 2^{\circ}\text{C}$ Humidity: $85\% \pm 2\text{RH}$ Rated working voltage applied Time: 500 (+24) hours Test after placing in ambient temperature for 1~2hours

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Specifications are subject to change without notice.

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